









PRODUCT DATASHEET



- ► PLCC2
- ➤ 3020 Series
- ► Red (625nm)

N0R07S02







3020 Series

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Release Date: 28 February 2014 Version: A1.0

APPLICATIONS:

- Backlighting
- Indicator
- Switch Lighting
- **Decoration Lighting**
- Light Bar

Package: PLCC White SMT Package

Forward Current: 60mA Forward Voltage (typ.): 2.2V

Luminous Flux (typ.): 1250mcd @60mA

Colour: Red

FEATURES:

Wavelength: 625nm Viewing angle: 120°

Materials:

Die: AlGaInP

Resin: Silicon (Water Clear) Operating Temperature: -40~+85°C

Storage Temperature: -40~+100°C

ESD: 2000V

Grouping parameters:

Forward voltage

Luminous flux

Wavelength

Soldering methods: IR Reflow soldering Preconditioning: acc. to JEDEC Level 3

Packing: 8mm tape with 2000/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	60	mA
Peak Forward Current Duty 1/10@10KHz	I _{FP}	90	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	PD	156	mW
Electrostatic Discharge	ESD	2000	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

Darameter	Symbol	Values		Unit	Test	
Parameter	Зуппоот	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	1.6		2.6	V	I _F =60mA
Luminous Intensity	I _V	800	1250	2000	mcd	I _F =60mA
Dominant Wavelength	λ_{D}		625		nm	I _F =60mA
Spectral Line Half Bandwidth	Δλ		20		nm	I _F =60mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =60mA

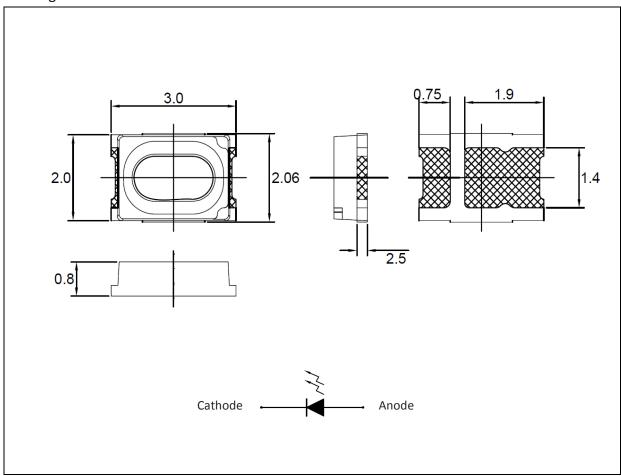
^{1.} Luminous intensity (Iv) $\pm 15\%$, Forward Voltage (VF) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 5\%$, CRI ± 3

^{2.} IS standard testing



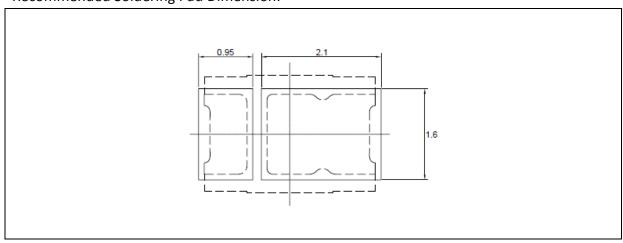
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 60 \text{mA}$):

Code	Min.	Max.	Unit
1	1.6	1.7	
2	1.7	1.8	
3	1.8	1.9	
4	1.9	2.0	
5	2.0	2.1	V
6	2.1	2.2	V
7	2.2	2.3	
8	2.3	2.4	
9	2.4	2.5	
10	2.5	2.6	

Luminous Flux Classifications ($I_F = 60 \text{mA}$):

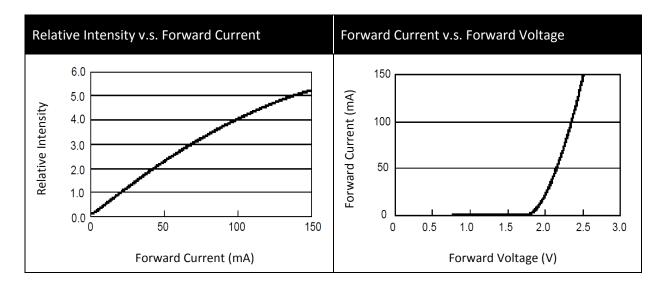
Code	Min.	Max.	Unit
AV1	800	1000	
AV2	1000	1250	mad
AW1	1250	1600	mcd
AW2	1600	2000	

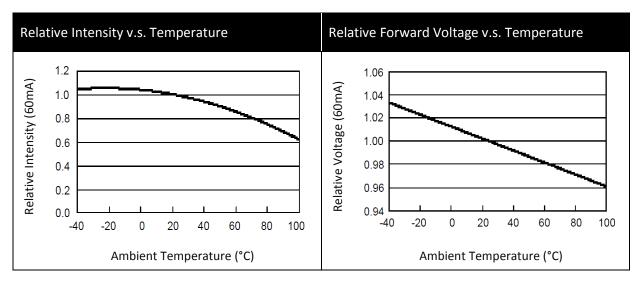
Dominant Wavelength Classifications ($I_F = 60 \text{mA}$):

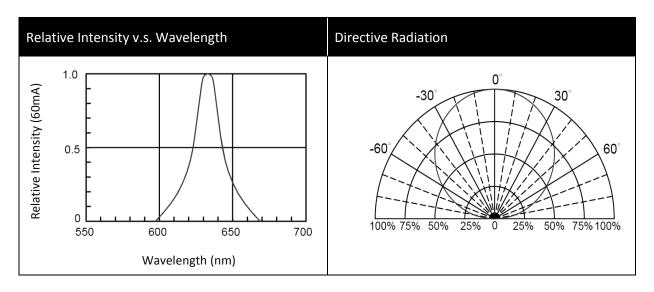
Code	Min.	Max.	Unit
20	616	619	
21	619	622	
22	622	625	nm
23	625	628	nm
24	628	631	
25	631	634	



ELECTRO-OPTICAL CHARACTERISTICS:



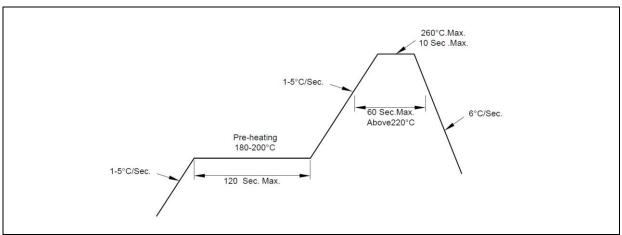






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



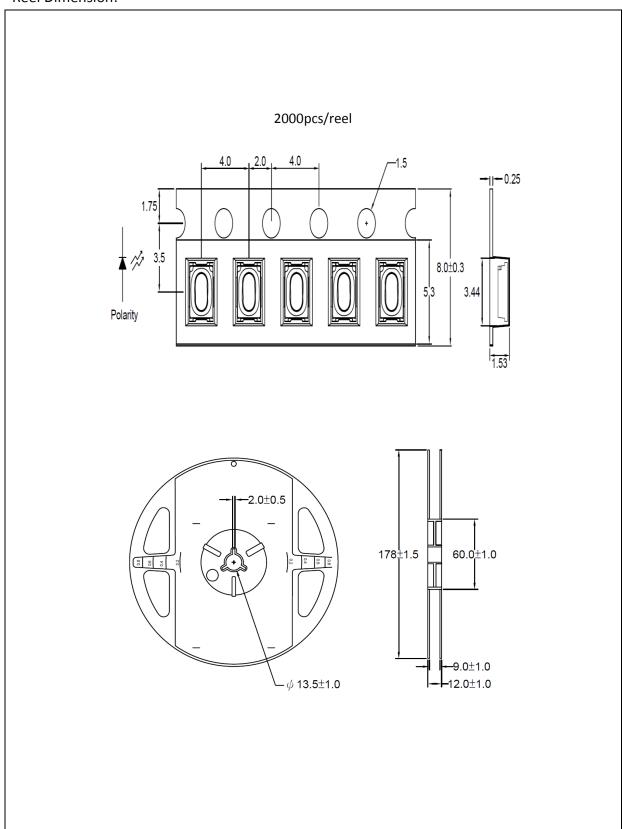
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

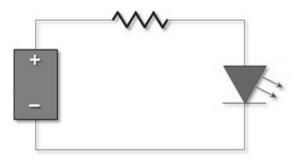
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	28/02/2014	Datasheet set-up.